

Themis RES-32XR3/FIO Rugged Enterprise Server



New Intel Four or Six Core Xeon based 3U Server With Front I/O

Themis' new RES-32XR3/FIO, a 3 Rack Unit (3U) Dual-Processor server, with all I/O accessible from the front of the machine. Power supplies, disk drives, Gigabit Ethernet controllers and graphics port are also front panel accessible. The RES-32XR3/FIO features a shallow 17.0 inch, 431.8mm, chassis depth. Front access and shallow depth make the RES-32XR3/FIO and ideal solution for space constrained environments.

The RES-32XR3/FIO combines the robust design of the Rugged Enterprise Server (RES) family, with the latest 5500 and 5600 series Intel® Xeon® processors. The rugged RES-32XR3/FIO reflects Themis' extensive expertise, designing high performance systems for use in demanding environments. This new system combines the Intel four and six core Xeon processors, with Themis' advanced thermal and mechanical design techniques, to achieve I/O configuration flexibility and high reliability in high shock and vibration environments.

The RES-32XR3/FIO can be configured with one or two four- or six-core Intel Xeon processors. Featuring multiple expansion slots, extensive high speed I/O, and multiple storage options the RES-32XR3/FIO allows users versatile configurability and system expansion. The RES-22XR3/FIO is easily expanded through the addition of commercially available, off the shelf GPU and IO controllers, to meet current and planned system requirements.

RES-XR3 Family Features:

Mechanical

- Designed for High Reliability in harsh operating environments
- Rack-optimized design for unique user requirements
- Extensive use of specially coated aluminum for light weight and corrosion resistance.
- Non-magnetic stainless steel in selected areas to add strength and stiffness
- Modular design for easy upgrade and service
- Optional Rack-Mount Slides
- Airflow direction: Front to Rear

Management and Operating System

- Suspend to RAM and Wake-on-LAN system management
- IPMI v2.0 support
- Linux® and Windows® OS support

RES-32XR3/FIO Specifications:

- One or 5500 or 5600 Series Intel Xeon Processors
- Up to 144GB DDR3 ECC memory
- Dimensions (HWD): 3U x 17" x 17.0"
133 mm x 431.8 mm x 431.8 mm

Expansion Slots accessible from the Front:

- Up to seven (7) PCI-E Slots
- PCI-X and PCI available on some configurations
- Expansion slots vary with configuration

Environmental*

- Operating Shock: 3 axis, 35G, 25ms
- Operating Vibration: 3.0 Grms, 8 Hz to 2000 Hz
- Operating Temperature: 0°C – Up to 55°C
- Humidity: up to 90% non-condensing
- MIL-STD-810G (Shock and Vibration)

* Environmental specifications are configuration dependent.

Reliability

- Hot Swappable fans
- Power Supply Options (hot swappable):
 - Single or redundant 750 Watt 110/220 VAC, (50/60Hz, 400Hz)
 - Single or redundant 500 Watt 18-36 VDC 32 Amp
 - Single or redundant 650 Watt 36-72 VDC 18 Amp
- Hot Swappable Disk Drives
- Zero-Channel RAID Support

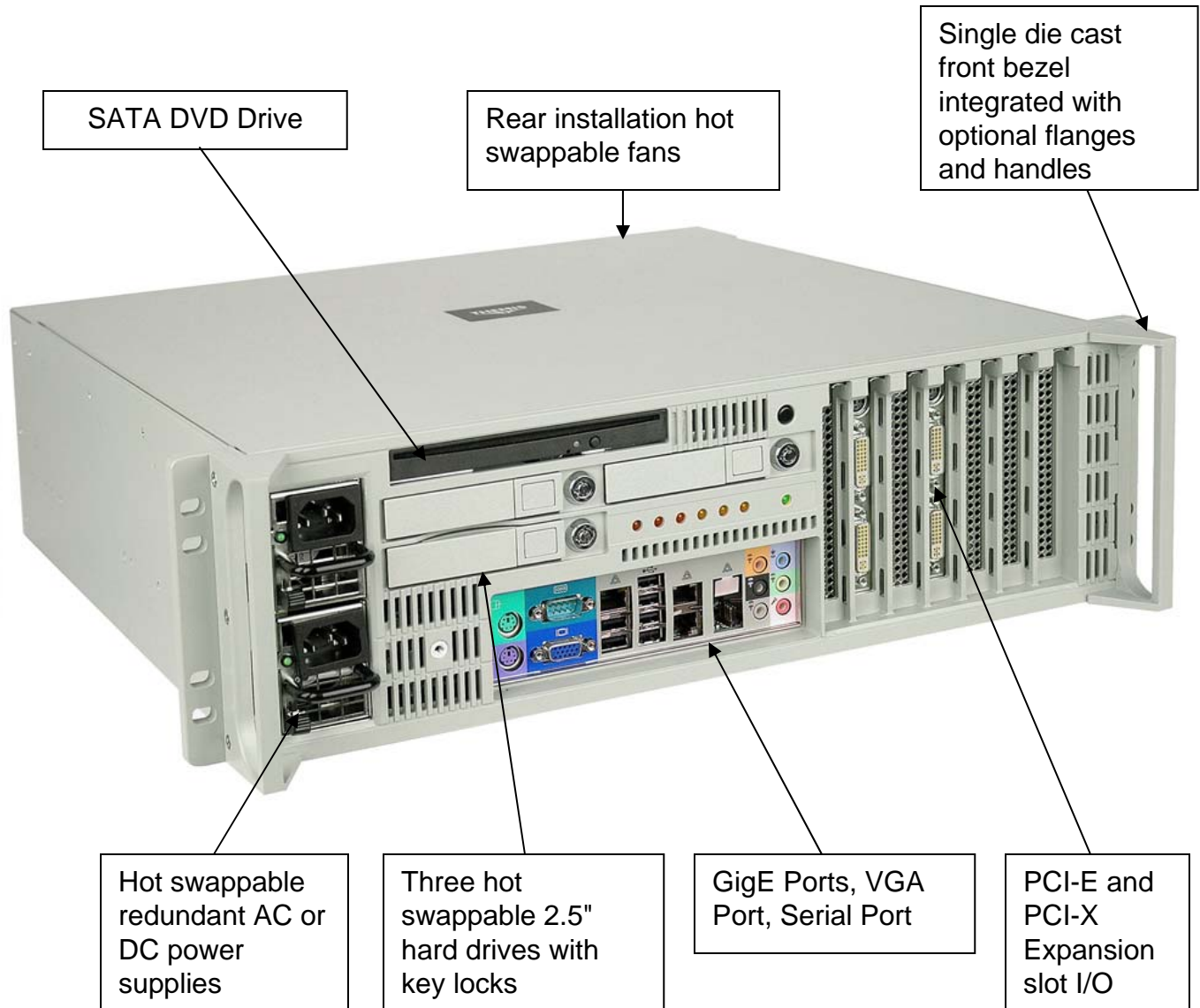
Front panel access and I/O:

- Up to Three(3) Removable 2.5" SATA or SAS Drives
- CD-RW/DVD-RW Drive (optional)
- Status LEDs, power switch
- Two (2) Gigabit Ethernet Ports (RJ45)
- One (1) or Two (2) RS-232 Serial Port (DB9)
- PS/2 Keyboard and Mouse Ports
- Up to six (6) USB 2.0 Ports
- Power connector and switch
- One (1) VGA Port in some configurations

* Front panel I/O will vary with configuration



RES-32XR3/FIO



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